

Filogel gel resin, 200 ml.

Art.nr. 804309



Application:

Filogel is a re-enterable cold curing 2-component non urethane encapsulating gel.

The resin is suitable for telecommunication applications to avoid damage caused by moisture. It is also suitable for insulation of low voltage connections and for the sealing of other electronic parts, especially when no mechanical stress is allowed (even at very low temperatures). For changing the installation or for repairing it, the resin can be removed very easily.

Properties:

- Free of Iso-cyanates, epoxides and silicones
- Not classified according to the EC regulations
- Medium viscosity while pouring
- Good adhesion to metals, minerals and many plastics
- Excellent hydrophobic behaviour

Technical specifications:

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|---------|--|-------------------------------------|
| Mixture | Mixing ratio resin/hardener | 1:1 |
| | Viscosity/ 20°C | approx. 1.000 cps |
| | Colour | transparent amber |
| | Density | 0,91 g/cm ³ |
| | Potlife/ 20°C | approx. 20 min. |
| | Geltime/ 20°C | approx. 50 min. |
| | Temperature resistance | long time 80°C short time 120 °C |
| | Elongation at break | 95 % |
| | Corrosion of copper (MS17000, section 1139) | non corrosive |
| | Insulation resistance @ 500 V DC | 1,2 x 10 ¹² ohm |
| | Volume resistivity @ 500 V DC | 0,6 x 10 ¹³ ohm.cm |
| | Water sensitivity (TA-NWT-000354) | 0% |
| | Water absorbtion (ASTM D570) | 0,36 % |
| | Chemical resistance against mineral oil, 2n H ₂ SO ₄ , CaCO ₃ -solution | no visible degradation |

Subject to change without notice

Cable joints • Sealing systems • Customer specific solutions